NGUYEN HUU ANH

DoB: 30-09-1993 | Phone: 0941-980-911 | Email: [nghanh0993@outlook.com](mailto:nghanh0993@outlook.com) | Add: Q9, Ho Chi Minh City

**About Me** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Over 4 years of experience in software development for semiconductor equipment (Wire Bonder UTC-3000, UTC-5000, UTC-5100 and Bump Bonder SBB-5200).

Strong knowledge about C, C++, OOP programming and MFC Framework.

Acknowledge about SECS/GEM, TCP/IP protocol, SEMI G84 (Specification for Strip Map Protocol).

Additional programming with Python, CSharp, VB.NET, Auto LISP.

Familiar with Visual Studio, Team Foundation Server (TFS), Git, Visual SourceSafe, IBM Lotus Notes.

Ability to writing and reading English documents.

**Experience** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**SHINKAWA VIETNAM CO., LTD**

Software Engineer – R&D TEAM *Mar. 2018 to Oct. 2020*

Software Engineer – DESIGN TEAM*Nov. 2016 to Mar. 2018*

**Education** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**HCMC INDUSTRY AND TRADE COLLEGE** – Bachelor Degree *Nov. 2012 – Mar. 2016*

**Specialty** – Information Technology.